



May 4, 2005

Bay Area Compliance Lab Corp.
230 Commercial Street
Sunnyvale, CA 94085

RE: Change notice of FCC sample

Dear Mrs. Wen,

I summarized our changes we made since you tested our sample for FCC certification in last October. We made following changes from previous sample to improve the audio quality and fix some noise issue.

For Base unit

1. Added capacitors to audio circuit and digital signal line to reduce digital noise and to bypass RF signal.
2. Added shield can at the CPU circuit to reduce digital noise from main CPU clock.
3. Added shield can at the interface circuit of Cellular module to reduce switching noise from the module.
4. Changed feeding method of RF signal from Cellular module to antenna. There was a short connection wire in between RF cable from module and antenna in the previous sample but new sample connects RF cable from module to antenna directly to reduce unwanted radiated RF signal to internal audio circuitry.
5. Added conductive paint to the bottom plastic enclosure to reduce interference of radiated RF signal from antenna to internal audio circuitry.
6. PWB (Printed Wiring Board): Modified layout according to above mentioned changes.

For Handset

1. Added capacitors to audio circuit and digital line to reduce noise and to bypass RF signal.
2. PWB (Printed Wiring Board): Modified layout according to above mentioned changes.

There are no changes made to RF circuitry because we use the modules both for GSM and 2.4GHz cordless part, which are supplied as standard component by Wavecom and National Semiconductor. We have no way to access to their RF circuitry.

Should you have any question or need more information please feel free to contact me.

Thank you.

Waxess Inc.
VP of Engineering
Hidekazu Nakama

A handwritten signature in blue ink, appearing to read "H. Nakama", written over the printed name.